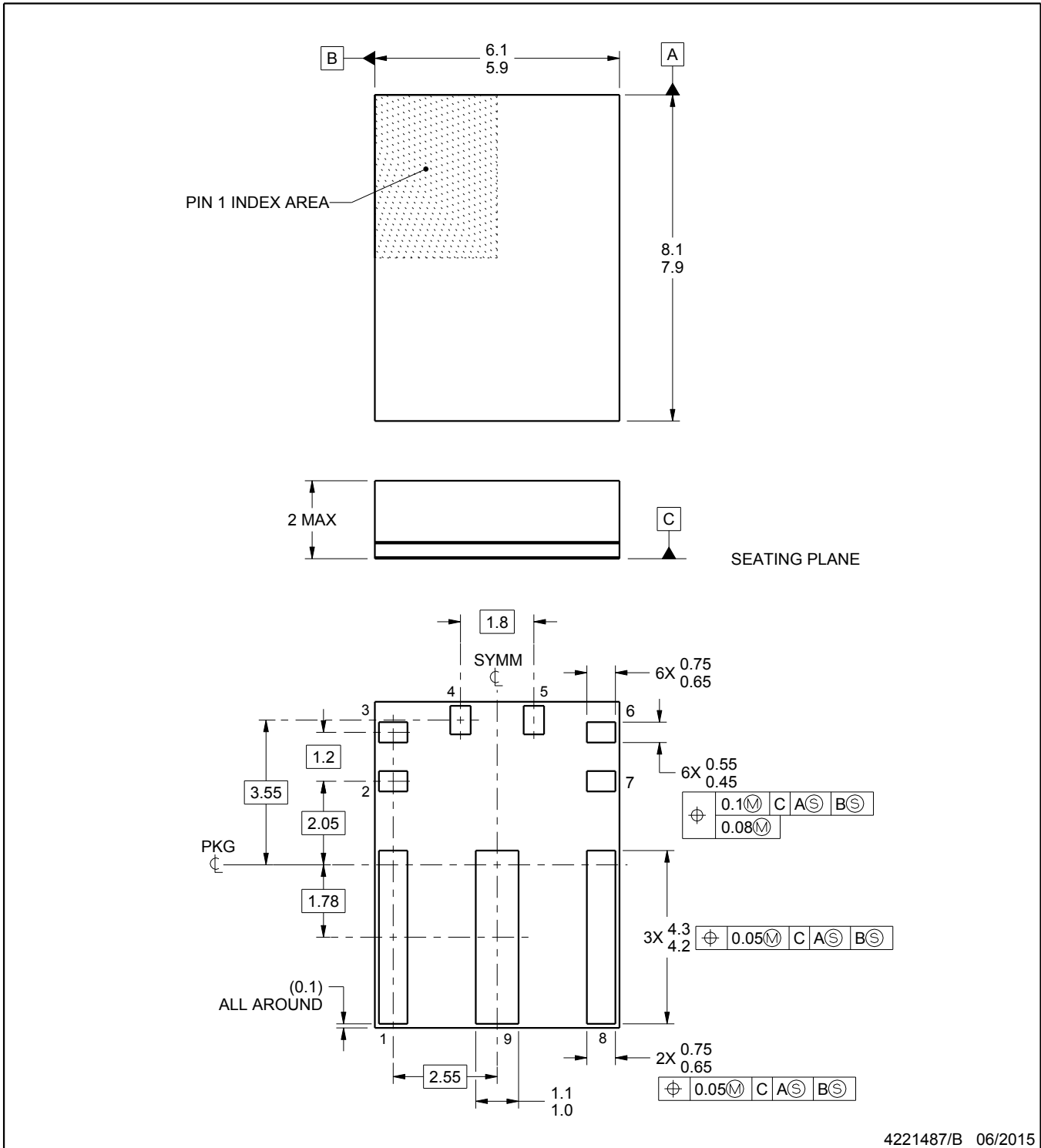


PACKAGE OUTLINE

MOF0009A

QFM - 2 mm max height

QUAD FLAT MODULE



NOTES:

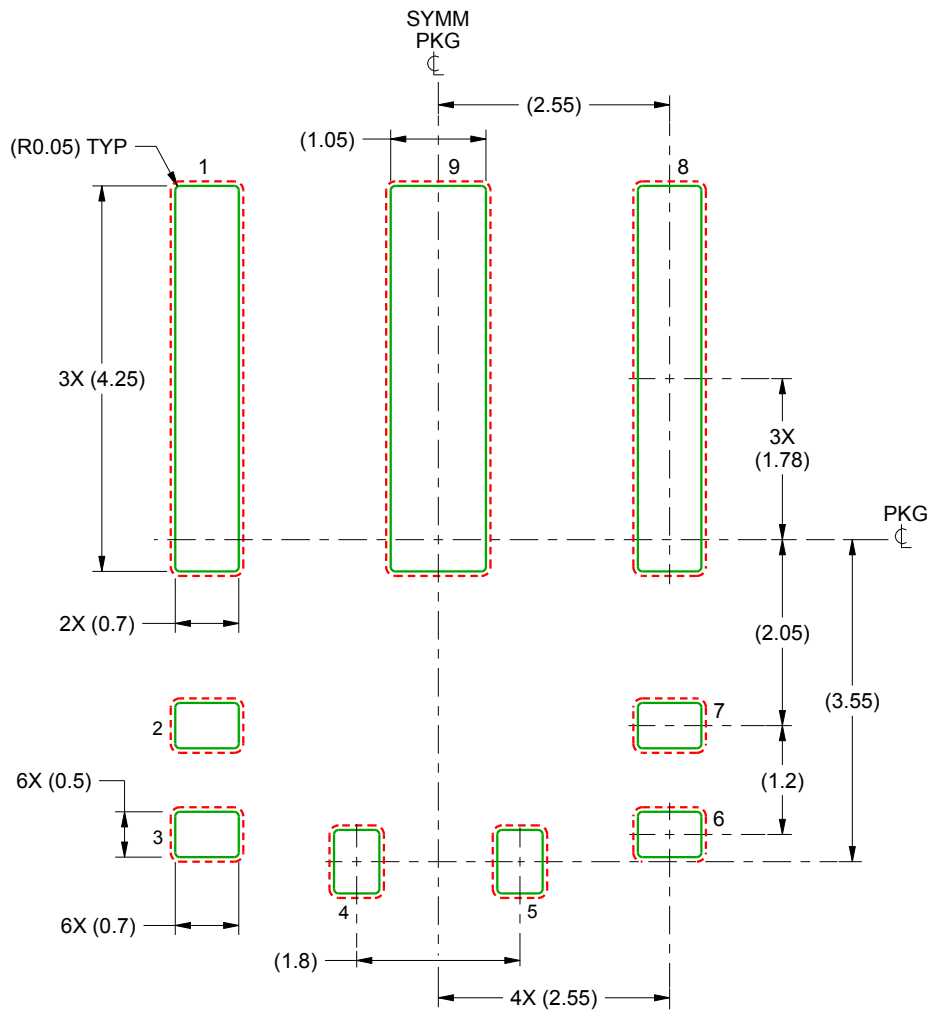
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

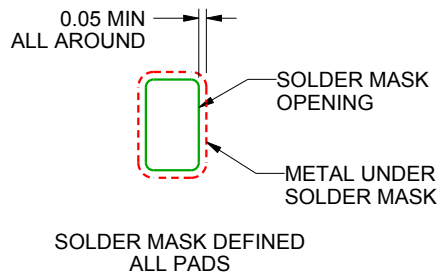
MOF0009A

QFM - 2 mm max height

QUAD FLAT MODULE



LAND PATTERN EXAMPLE
SCALE:12X



4221487/B 06/2015

NOTES: (continued)

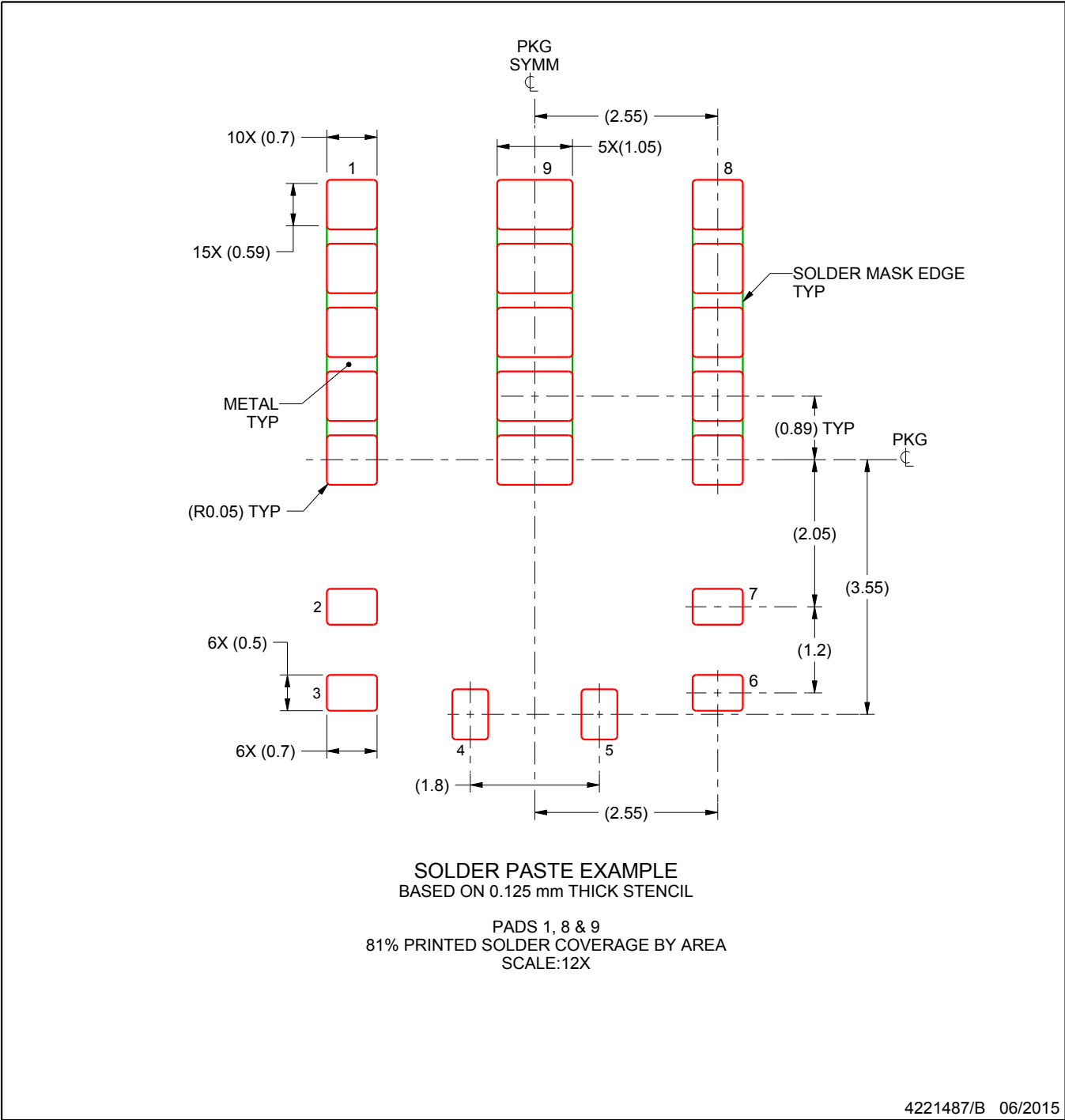
3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

MOF0009A

QFM - 2 mm max height

QUAD FLAT MODULE



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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